

ABSTRACT

10 A semiconductor component includes a chip on
board leadframe, a semiconductor die back bonded and
wire bonded to the leadframe, an encapsulant on the
die and an area array of terminal contacts on the
leadframe. The leadframe includes leadfingers,
interconnect bonding sites for wire bonding the die,
terminal bonding sites for the terminal contacts, and
bus bars which electrically connect selected
15 leadfingers to one another. The interconnect bonding
sites are located on the leadframe relative to the bus
bars such that shorting to the bus bars by wire
interconnects is eliminated. A method for fabricating
the component includes the steps of attaching the die
20 to the leadframe, bonding the wire interconnects to
the die and to the interconnect bonding sites, forming
the encapsulant, and then forming the terminal
contacts on the terminal bonding sites.